

Electronic Patent Application Fee Transmittal

Application Number:				
Filing Date:				
Title of Invention:	Method of Forming Thin SGOI Wafers with High Relaxation and Low Stacking Fault Defect Density			
First Named Inventor:	Huajie Chen			
Filer:	Yuanmin Cai			
Attorney Docket Number:	FIS920030342US1			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
National Stage Fee	1631	1	300	300
Natl Stage Search - U.S. as IPE or ISA	1640	1	0	0
National Stage Exam Fee - U.S. was IPEA	1643	1	0	0
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				300